

LINEAR TECHNOLOGY MATERIALS DECLARATION

LT3020IMS8-1.2#TRPBF		(Engineering Calculation)		MSOP				
(printed on: 7/16/2011 1:12:31 PM)				TOTAL MASS (g):		0.02705203		
COMPONENT	VENDOR/	CONSTITUENT	CAS	CONSTITUENT	CONSTITUENT	CONSTITUENT		
MATERIAL	INDUSTRY NAMES	NAME	NUMBER	MASS (g)	(PPM) OF MATERIAL	(PPM) OF TOTAL PKG.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.001815	1000000	67092.94		
Die Coat	Dow Corning	Silicone	67762-90-7	0	0	0		
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.010433	975000	385664.3		
		Iron (Fe)	7439-89-6	0.000257	24000	9500.213		
		Phosphorus (P)	7723-14-0	3.00E-06	300	110.8974		
		Zinc (Zn)	7440-66-6	7.00E-06	700	258.7607		
		Nickel (Ni)	7440-02-0	0	0	0		
		Silicon (Si)	7440-21-3	0	0	0		
		Magnesium (Mg)	7439-95-4	0	0	0		
		Tin (Sn)	7440-31-5	0	0	0		
		Lead Frame Total:				0.0107	1000000	395534.2
Plating	PMI	Exter. Plating Pb	7439-92-1	0	0	0		
		Exter. Plating Sn	7440-31-5	0.000710025	1000000	26246.65		
		External Plating Total:				0.000710025	1000000	26246.65
		Inter. Plating Ni	7440-02-0	0	0	0		
		Inter. Plating Ag	7440-22-4	8.60E-05	1000000	3179.059		
		Internal Plating Total:				8.60E-05	1000000	3179.059
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.000668	750000	24693.16		
		Tin (Sn)	7440-31-5	0	0	0		
		Lead (Pb)	7439-92-1	0	0	0		
		Silica (SiO2)	60676-86-0	0	0	0		
		Metal Oxide		0	0	0		
		Antimony (Sb)	7440-36-0	0	0	0		
		Resin (EP)		0.000223	250000	8243.375		
Die Attach Total:				0.000891	1000000	32936.53		
Encapsulation	MULTI-AROMATIC RESIN Br/Sb FREE	Resin (EP)		0.001659	130000	61326.27		
		Bromine (Br)	40039-93-8	0	0	0		
		Silica (SiO2)	60676-86-0	0.010591	830000	391504.9		
		Antimony	1309-64-4	0	0	0		
		Trioxide (Sb2O3)						
		Metal Hydroxid		0.000447	35000	16523.71		
		Carbon Black (C)	1333-86-4	6.40E-05	5000	2365.812		
Encapsulation Total:				0.012761	1000000	471720.7		
Bond Wire	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	8.90E-05	1000000	3289.957		
Estimated								
				TOTAL MASS (g):		0.02705203		